

## ORGANIZING INFORMATION

### THE CONFERENCE IS HELD AT:

Střední škola informatiky  
Čichnova 23, 624 00 BRNO-Komín

### **How to get there: see incl. plan by a car**

From the Brno Trade Fair Exhibition Centre go in direction Brno-dam. After approx. 4 km you will see the OPEL, TOYOTA car shop centre, on the left side. At the crossroads in front of the OPEL, TOYOTA go to the left, at the next crossroads to the right and on the right side you will see an educational centre:

Střední škola informatiky  
street Čichnova 23, BRNO-Komín

### BINDING APPLICATIONS:

Will be mailed together with obligatory demand for accommodation with meals before **October 14, 2022** to the address:

SMT-INFO consortium  
Údolní 53, 602 00 Brno  
CZECH REPUBLIC  
e-mail: [info@smtinfo.cz](mailto:info@smtinfo.cz)  
e-mail: [smtinfocz@gmail.com](mailto:smtinfocz@gmail.com)

### REGISTRATION:

In the conference hall  
**October 18, 2022**                      **8.15–8.40 a.m.**

### PROFESSIONAL GUARANTOR:

SMT-INFO, Údolní 53, 602 00 Brno  
CZECH REPUBLIC

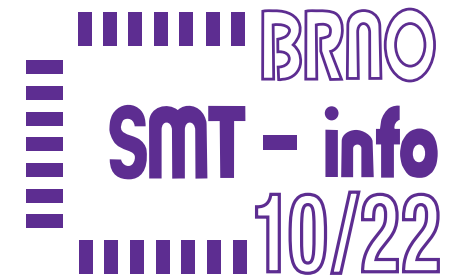
tel.:     **00420-541 146 113**  
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e-mail: [info@smtinfo.cz](mailto:info@smtinfo.cz), [smtinfocz@gmail.com](mailto:smtinfocz@gmail.com)  
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## SMT-INFO CONSORTIUM

in cooperation with

**BRNO UNIVERSITY OF TECHNOLOGY**  
**and**  
**SEC. SCHOOL OF INFORMATICS BRNO**

have the pleasure to invite you  
to participate in the international conference



**SOLDERING AND CLEANING**  
**PCB's IN ELECTRONICS**

**NEW TRENDS**  
**IN MICROELECTRONICS**

**SOLDER JOINT DEFECTS**

BRNO, October 18, 2022  
SŠ informatiky  
Čichnova 23, Brno-Komín

event. code 10/22

Media Partner of the Conference is the Magazine  
PCB ELECTRONICS A-Z



### **CONFERENCE ORIENTATION:**

- SOLDERING AND CLEANING IN ELECTRONICS
- NEW TRENDS IN MICROELECTRONICS
- TECHNIQUES IN REPAIRING
- SOLDER JOINT DEFECTS

### **PROFESSIONAL OFFER**

- Conference participants will be acquainted with the latest information on above mentioned topics presented by specialist from prestigious companies.
- In a room adjacent the lecture theatre, the following company stands will be installed and professional literature and demonstration equipment will be offered there:

#### **ABE.TEC**

#### **ADOPTSMT EUROPE**

#### **AMTEST GROUP**

#### **PAN ELECTRONICS**

- Advertisement tables will be available for the conference participants and visitors, providing propagation of their own products and offer of non-used/used technological equipment and services.

### **THEMATIC ORIENTATION OF OTHER EVENTS**

#### **ORGANIZED BY SMT-INFO:**

#### **SMT-INFO 02/23**

**Brno, February 7, 2023**

Technical and Business Seminar

- PCB DESIGN SYSTEMS
- PCB PRODUCTION AND DEFECTS
- COMPLEX PRODUCTION LINES FOR MODERN ASSEMBLY
- INSPECTION SYSTEMS

#### **PROFESSIONAL GUARANTOR:**

**SMT-INFO CONSORTIUM, Údolní 53, 602 00 Brno**

**e-mail: info@smtinfo.cz, smtinfocz@gmail.com**

**mobil: 00420-602 542 966**

### **CONFERENCE SCHEDULE**

#### **Tuesday, October 18, 2022**

- |   |   |
|---|---|
| 8.40 - Opening, Introduction  | 14.00 - Revolution inspection method of protective coatings on PCB<br>/M. Drlík, IMT Technologies&Solutions, Valašské Meziříčí/ |
| 8.45 - Thermal processes and their effect in reflow soldering<br>/K. Dušek, FEL ČVUT Praha/   | 14.40 - New trends in soldering materials NEVO<br>/N. Hrbek, AMTECH, NEVO Buchovice/  |
| 9.00 - 2D/3D measuring of assembled and non assembled PCBs with digital microscope SANXO<br>/M. Abel, ABE.TEC Ostřešany/  | 15.10 - 3 strategies to overcome BTC voiding in 2022<br>/P. Bettinec, A. Sedlák, AIM SOLDER Brno/                               |
| 9.10 - Technology of laser soldering JAPAN UNIX<br>/P. Lacko, QUIPTech Brno/  | 15.40 - Validation of manual soldering process with soldering station Hakko FN-1010<br>/M. Abel, ABE.TEC, Ostřešany/            |
| 9.50 - Break – Coffee, Refreshment  | 15.50 - UV and UV LED curable materials for PCB conformal coating<br>/B. Györfy, HUMISEAL, R. Ďuriš, AMTEST GROUP Slovakia/     |
| 10.10 - Development of High Reliability Low Melting Point Alloys<br>/N. Suli, MAC DERMID Alpha Hungary, M. Cichra, ERMEG Liberec/   | 16.10 - Heating Factor<br>/J. Dokoupil, FEKT VUT Brno, RESIDEO Brno/  |
| 11.10 - PCBs for complicate interconnection and thermal management of components<br>/O. Šimek, PRAGOBOARD Praha/  | 16.20 - Discussion, Closing of Conference   |
| 11.50 - Discussion  |   |
| 12.00 - Difference between static and dynamic mixing of 2K materials for potting and thermal interface applications<br>/M. Rieger, BDTRONIC, J. Vondráček, AMTEST GROUP Brno/ |   |
| 12.30 - Heat transfer in convection soldering systems<br>/M. Hurban, REHM Příbor/   |   |
| 12.50 - Quality of cleaning very complicated assemblies and process automatization<br>/V. Sítko, PBT WORKS Rožnov p. Radhoštěm/   |   |
| 13.20 - Lunch   |   |

**Lectures in English and German  
will be interpreted.  
Program changes reserved.**